

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Akram et al.

Serial No.: 09/944,499

Filed: August 30, 2001

For: STABILIZERS FOR FLIP-CHIP TYPE

SEMICONDUCTOR DEVICES AND

SEMICONDUCTOR DEVICE

COMPONENTS AND ASSEMBLIES INCLUDING THE SAME (Amended)

Confirmation No.: 4371

Examiner: A. Chambliss

Group Art Unit: 2827

Attorney Docket No.: 2269-3936.1US

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

April 8, 2003

Date

Deidra Pfeil
Name (Type/Print)

LETTER TO THE OFFICIAL DRAFTSPERSON

Box Issue Fee Commissioner for Patents Washington, D.C. 20231

Sir:

Applicants submit herewith revised FIGS.1, 20 and 21which correct errors in the drawings. Specifically, FIG. 1 has been revised to delete the reference numerals "206", "208" and "212" with appropriate lead lines; FIG. 20 has been revised to delete the reference numerals "116", "124" and "148" with appropriate lead lines and FIG. 21 has been revised to change reference numerals "130A" to--130-- and "130B" to --130--. Attached is a copy of the drawings with the proposed changes marked in red.

No new matter has been added. Approval of the proposed revisions is respectfully requested.

Respectfully submitted,

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Date: April 8, 2003

BGP/djp

Enclosures: Drawings with changes marked in red

Document in ProLaw